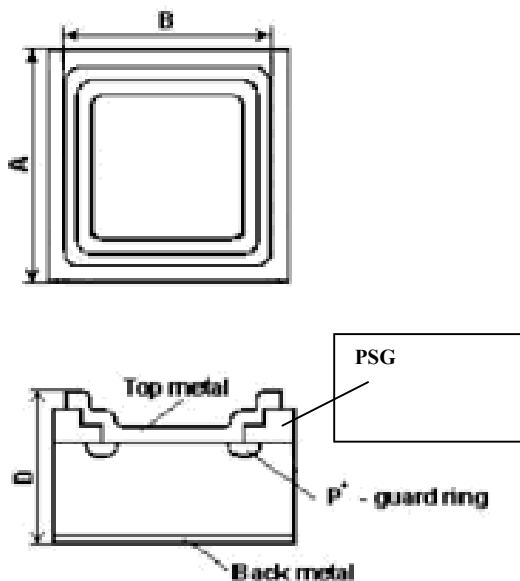


**SCHOTTKY DIODES. KDS- 10040R.**  
PRELIMINARY.



Nov. 2011.

VSP-MIKRON		<b>10A/40V. Die Size-115mil.</b>		
Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=10mA$	$V_B$	V	40	45
Average Rectified Forward Current	$I_{F(AV)}$	A	10,0	-
DC Forward Voltage @ $25^\circ C, I_F=10,0A$	$V_F$	V	0,40	0,38
Maximum Reverse Current @ $25^\circ C, V_R=45V$ @ $25^\circ C, V_R=40V$ @ $100^\circ C, V_R=40V$	$I_R$	MA	- 3,5 120,0	3,5 2,5 100,0
Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)	$I_{FSM}$	A	200	-
Peak Repetitive Reverse Surge Current @ $2,0\mu s, f=1kHz., T_J < 150^\circ C.$	$I_{RRM}$	A	4,5	
Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.	ESD	kV	$\pm 8$ (contact)	
Voltage Rate of Change	$dV/dt$	$V/\mu S$	10.000	
Operating Junction Temperature	$T_J$	$^\circ C$	125	



DIM	ITEM	$\mu m$
$A_x$ $A_y$	Die Size	2920
$B_x$ $B_y$	Top Metal Size	2780
D	Thickness	300max.
Scribe line Width		60

*Top metal:* a) **Al** – for Wire Bonding;  
b) **Al-Ni-Ag** – for Soldering.  
*Backside metal:* **Ti-Ni-Ag**.